TOSHIBA DIODE SILICON EPITAXIAL PLANAR TYPE

HN2D01F

ULTRA HIGH SPEED SWITCHING APPLICATION.

HN2D01F is composed of 3 independent diodes.

• Low Forward Voltage : V_{F(3)}=0.98V (Typ.)

 \bullet Fast Reverse Recovery Time : t_{rr} = 1.6ns (Typ.)

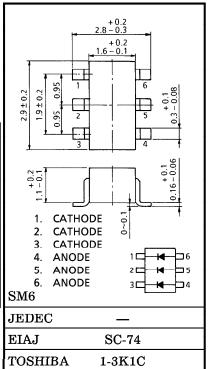
• Small Total Capacitance : C_T=0.5pF (Typ.)

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Maximum (Peak) Reverse Voltage	$V_{\mathbf{RM}}$	85	V	
Reverse Voltage	$v_{ m R}$	80	V	
Maximum (Peak) Forward Current	$I_{ ext{FM}}$	240 (*)	mA	
Average Forward Current	IO	80 (*)	mA	
Surge Current (10ms)	I_{FSM}	1 (*)	Α	
Power Dissipation	P	300	mW	
Junction Temperature	T_{j}	125	$^{\circ}\mathrm{C}$	
Storage Temperature Range	$\mathrm{T_{stg}}$	-55~125	°C	

(*) This is the Maximum Rating of single diode (Q1 or Q2 or Q3). In the case of using 2 or 3 diodes, the Maximum Ratings per diode is 75% of the single diode one.

Unit in mm

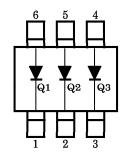


Weight: 0.015g

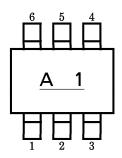
ELECTRICAL CHARACTERISTICS (Q1, Q2, Q3 COMMON Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V _{F(1)}	I _F =1mA	_	0.62	_	V
	$V_{F(2)}$	$I_{\mathbf{F}} = 10 \text{mA}$	_	0.75	_	
	$V_{F(3)}$	$I_{\rm F}$ =100mA	_	0.98	1.20	
Reverse Current	I _{R (1)}	$V_R = 30V$	_	_	0.1	$\mu \mathbf{A}$
	I _{R (2)}	$V_R=80V$	_		0.5	
Total Capacitance	C_{T}	$V_R=0$, f=1MHz		0.5	3.0	рF
Reverse Recovery Time	t _{rr}	I _F =10mA (Fig.1)	_	1.6	4.0	ns

PIN ASSIGNMENT (TOP VIEW)



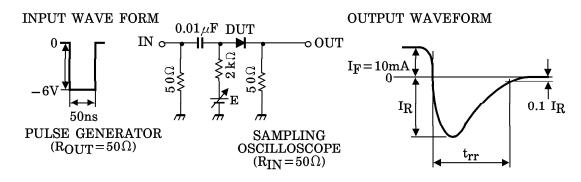
MARKING

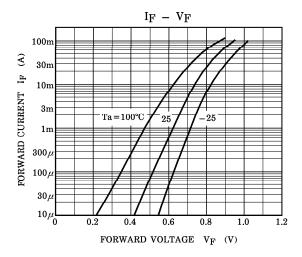


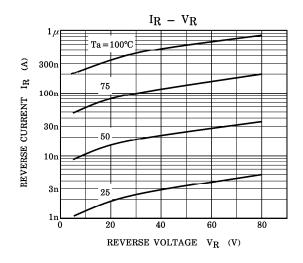
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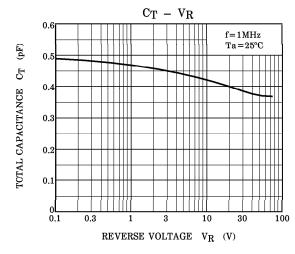
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Fig.1 : REVERSE RECOVERY TIME (t_{rr}) TEST CIRCUIT









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